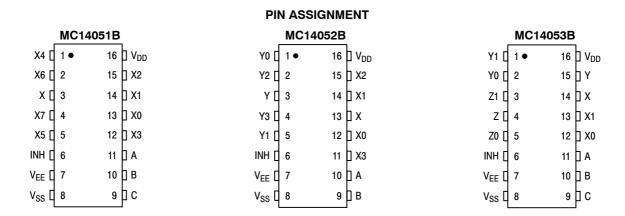


Note: Control Inputs referenced to  $V_{SS}$ , Analog Inputs and Outputs reference to  $V_{EE}$ .  $V_{EE}$  must be  $\leq V_{SS}$ .



#### **ELECTRICAL CHARACTERISTICS**

				- 55°C			25°C		125°C		
Characteristic	Symbol	V <sub>DD</sub>	Test Conditions	Min	Max	Min	Typ (Note 2)	Max	Min	Max	Unit
SUPPLY REQUIREMENTS	(Voltages	Referer	nced to V <sub>EE</sub> )	ı		I	l.				
Power Supply Voltage Range	V <sub>DD</sub>	-	$V_{DD} - 3.0 \ge V_{SS} \ge V_{EE}$	3.0	18	3.0	-	18	3.0	18	V
Quiescent Current Per Package	I <sub>DD</sub>	5.0 10 15	$\label{eq:control Inputs: Vin = VSS or VDD,} V_{in} = V_{SS} \text{ or V}_{DD}, \\ Switch I/O: V_{EE} \leq V_{I/O} \leq V_{DD}, \text{ and } \Delta V_{switch} \leq 500 \text{ mV (Note 3)}$		5.0 10 20	- - -	0.005 0.010 0.015	5.0 10 20		150 300 600	μΑ
Total Supply Current (Dynamic Plus Quiescent, Per Package	I <sub>D(AV)</sub>	5.0 10 15	$T_A = 25^{\circ} C$ only (The channel component, $(V_{in} - V_{out})/R_{on}$ , is not included.)		Typical	(	(0.07 μA/kHz (0.20 μA/kHz (0.36 μA/kHz	z) f + I <sub>DD</sub>			μΑ
CONTROL INPUTS — INHI	BIT, A, B,	C (Volta	ages Referenced to V <sub>SS</sub> )								
Low-Level Input Voltage	V <sub>IL</sub>	5.0 10 15	R <sub>on</sub> = per spec, I <sub>off</sub> = per spec	- - -	1.5 3.0 4.0	- - -	2.25 4.50 6.75	1.5 3.0 4.0	1 1 1	1.5 3.0 4.0	V
High-Level Input Voltage	V <sub>IH</sub>	5.0 10 15	R <sub>on</sub> = per spec, I <sub>off</sub> = per spec	3.5 7.0 11	- - -	3.5 7.0 11	2.75 5.50 8.25	- - -	3.5 7.0 11	- - -	>
Input Leakage Current	l <sub>in</sub>	15	V <sub>in</sub> = 0 or V <sub>DD</sub>	_	± 0.1	_	±0.00001	± 0.1	-	1.0	μΑ
Input Capacitance	C <sub>in</sub>	-		_	-	_	5.0	7.5	ı	-	рF
SWITCHES IN/OUT AND C	OMMONS	OUT/II	N — X, Y, Z (Voltages Refere	nced to	V <sub>EE</sub> )						
Recommended Peak-to-Peak Voltage Into or Out of the Switch	V <sub>I/O</sub>	-	Channel On or Off	0	V <sub>DD</sub>	0	-	V <sub>DD</sub>	0	V <sub>DD</sub>	$V_{PP}$
Recommended Static or Dynamic Voltage Across the Switch (Note 3) (Figure 5)	$\Delta V_{switch}$	-	Channel On	0	600	0	-	600	0	300	mV
Output Offset Voltage	V <sub>OO</sub>	_	V <sub>in</sub> = 0 V, No Load	_	-	-	10	_	-	-	μV
ON Resistance	R <sub>on</sub>	5.0 10 15	$\begin{split} \Delta V_{\text{Switch}} &\leq 500 \text{ mV} \\ \text{(Note 3) } V_{in} &= V_{IL} \text{ or } V_{IH} \\ \text{(Control), and } V_{in} &= \\ 0 \text{ to } V_{DD} \text{ (Switch)} \end{split}$	- - -	800 400 220	- - -	250 120 80	1050 500 280	1 1 1	1200 520 300	Ω
ΔON Resistance Between Any Two Channels in the Same Package	$\Delta R_{on}$	5.0 10 15		- - -	70 50 45	- - -	25 10 10	70 50 45	1 1	135 95 65	Ω
Off-Channel Leakage Current (Figure 10)	l <sub>off</sub>	15	V <sub>in</sub> = V <sub>IL</sub> or V <sub>IH</sub> (Control) Channel to Channel or Any One Channel	_	± 100	-	± 0.05	± 100	-	±1000	nA
Capacitance, Switch I/O	C <sub>I/O</sub>	_	Inhibit = V <sub>DD</sub>	_	-	-	10	-	-	-	pF
Capacitance, Common O/I	C <sub>O/I</sub>	-	Inhibit = V <sub>DD</sub> (MC14051B) (MC14052B) (MC14053B)	- - -	- - -	- - -	60 32 17	- - -	- - -	- - -	pF
Capacitance, Feedthrough (Channel Off)	C <sub>I/O</sub>	-	Pins Not Adjacent Pins Adjacent	-		-	0.15 0.47	1 1	1 1	-	pF

Data labeled "Typ" is not to be used for design purposes, but is intended as an indication of the IC's potential performance.
 For voltage drops across the switch (ΔV<sub>switch</sub>) > 600 mV ( > 300 mV at high temperature), excessive V<sub>DD</sub> current may be drawn, i.e. the current out of the switch may contain both V<sub>DD</sub> and switch input components. The reliability of the device will be unaffected unless the Maximum Ratings are exceeded. (See first page of this data sheet.)

ELECTRICAL CHARACTERISTICS (Note 4) (C<sub>L</sub> = 50 pF, T<sub>A</sub> = 25°C) (V<sub>EF</sub> ≤ V<sub>SS</sub> unless otherwise indicated)

Characteristic	Symbol	V <sub>DD</sub> – V <sub>EE</sub> Vdc	Typ (Note 5) All Types	Max	Unit
Propagation Delay Times (Figure 6) Switch Input to Switch Output ( $R_L = 1 \text{ k}\Omega$ ) MC14051	t <sub>PLH</sub> , t <sub>PHL</sub>				ns
$t_{PLH}$ , $t_{PHL}$ = (0.17 ns/pF) $C_L$ + 26.5 ns $t_{PLH}$ , $t_{PHL}$ = (0.08 ns/pF) $C_L$ + 11 ns $t_{PLH}$ , $t_{PHL}$ = (0.06 ns/pF) $C_L$ + 9.0 ns		5.0 10 15	35 15 12	90 40 30	
MC14052					ns
$t_{PLH}, t_{PHL} = (0.17 \text{ ns/pF}) \text{ C}_L + 21.5 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.08 \text{ ns/pF}) \text{ C}_L + 8.0 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.06 \text{ ns/pF}) \text{ C}_L + 7.0 \text{ ns}$		5.0 10 15	30 12 10	75 30 25	
$\begin{aligned} &\text{MC14053} \\ &\text{t}_{\text{PLH}},  \text{t}_{\text{PHL}} = (0.17  \text{ns/pF})  \text{C}_{\text{L}} + 16.5  \text{ns} \\ &\text{t}_{\text{PLH}},  \text{t}_{\text{PHL}} = (0.08  \text{ns/pF})  \text{C}_{\text{L}} + 4.0  \text{ns} \\ &\text{t}_{\text{PLH}},  \text{t}_{\text{PHL}} = (0.06  \text{ns/pF})  \text{C}_{\text{L}} + 3.0  \text{ns} \end{aligned}$		5.0 10 15	25 8.0 6.0	65 20 15	ns
Inhibit to Output ( $R_L = 10 \text{ k}\Omega$ , $V_{EE} = V_{SS}$ ) Output "1" or "0" to High Impedance, or High Impedance to "1" or "0" Level	t <sub>PHZ</sub> , t <sub>PLZ</sub> , t <sub>PZH</sub> , t <sub>PZL</sub>				ns
MC14051B		5.0 10 15	350 170 140	700 340 280	
MC14052B		5.0 10 15	300 155 125	600 310 250	ns
MC14053B		5.0 10 15	275 140 110	550 280 220	ns
Control Input to Output (R <sub>L</sub> = 1 k $\Omega$ , V <sub>EE</sub> = V <sub>SS</sub> ) MC14051B	t <sub>PLH</sub> , t <sub>PHL</sub>	5.0 10 15	360 160 120	720 320 240	ns
MC14052B		5.0 10 15	325 130 90	650 260 180	ns
MC14053B		5.0 10 15	300 120 80	600 240 160	ns
Second Harmonic Distortion $(R_L = 10K\Omega, f = 1 \text{ kHz}) V_{in} = 5 V_{PP}$	-	10	0.07	-	%
Bandwidth (Figure 7) $ (R_L = 50 \ \Omega, \ V_{in} = 1/2 \ (V_{DD} - V_{EE}) \ p-p, \ C_L = 50pF \\ 20 \ Log \ (V_{out}/V_{in}) = -3 \ dB) $	BW	10	17	-	MHz
Off Channel Feedthrough Attenuation (Figure 7) $R_L = 1K\Omega, \ V_{in} = 1/2 \ (V_{DD} - V_{EE}) \ p-p$ $f_{in} = 4.5 \ MHz - MC14051B$ $f_{in} = 30 \ MHz - MC14052B$ $f_{in} = 55 \ MHz - MC14053B$	-	10	- 50	-	dB
Channel Separation (Figure 8) $ (R_L = 1 \text{ k}\Omega, V_{in} = 1/2 \text{ (}V_{DD} V_{EE}\text{) p-p,} \\ f_{in} = 3.0 \text{ MHz} $	-	10	- 50	-	dB
Crosstalk, Control Input to Common O/I (Figure 9) $(R_1 = 1 \text{ k}\Omega, R_L = 10 \text{ k}\Omega$ Control $t_{TLH} = t_{THL} = 20 \text{ ns, Inhibit} = V_{SS})$	-	10	75	-	mV

The formulas given are for the typical characteristics only at 25°C.
 Data labelled "Typ" is not lo be used for design purposes but In intended as an indication of the IC's potential performance.

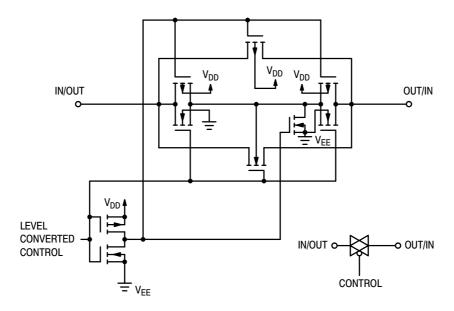


Figure 1. Switch Circuit Schematic

#### **TRUTH TABLE**

Cont	Control Inputs								
	S	elec	t	ON Switches					
Inhibit	C*	В	Α	MC14051B	MC14	1052B	MC14053B		
0	0	0	0	X0	Y0	X0	Z0	Y0	X0
0	0	0	1	X1	Y1	X1	Z0	Y0	X1
0	0	1	0	X2	Y2	X2	Z0	Y1	X0
0	0	1	1	Х3	Y3	Х3	Z0	Y1	X1
0	1	0	0	X4			Z1	Y0	X0
0	1	0	1	X5			Z1	Y0	X1
0	1	1	0	X6			Z1	Y1	X0
0	1	1	1	X7			Z1	Y1	X1
1	х	Х	Х	None	No	ne		None	

\*Not applicable for MC14052

x = Don't Care

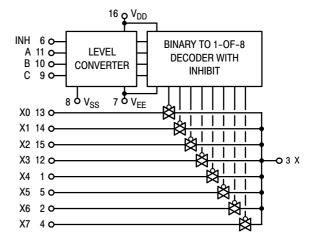


Figure 2. MC14051B Functional Diagram

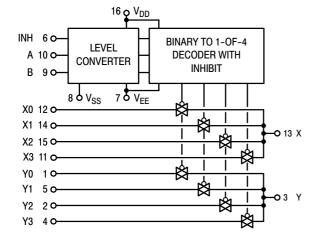


Figure 3. MC14052B Functional Diagram

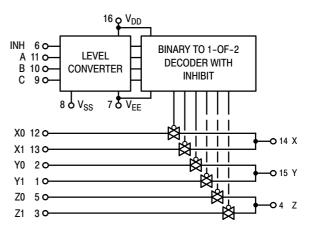


Figure 4. MC14053B Functional Diagram

#### **TEST CIRCUITS**

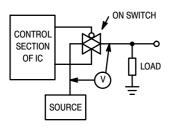


Figure 5.  $\Delta V$  Across Switch

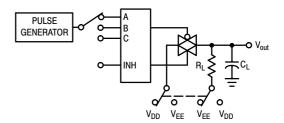


Figure 6. Propagation Delay Times, Control and Inhibit to Output

A, B, and C inputs used to turn ON or OFF the switch under test.

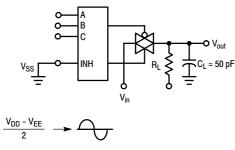


Figure 7. Bandwidth and Off-Channel Feedthrough Attenuation

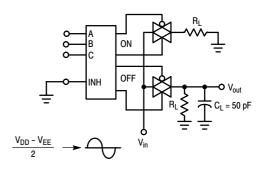


Figure 8. Channel Separation (Adjacent Channels Used For Setup)

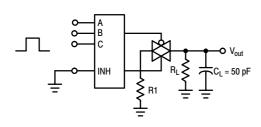


Figure 9. Crosstalk, Control Input to Common O/I

NOTE: See also Figures 7 and 8 in the MC14016B data sheet.

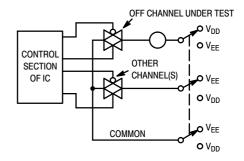


Figure 10. Off Channel Leakage

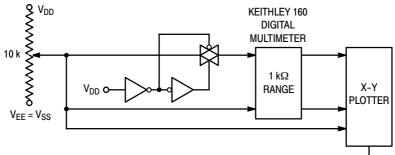
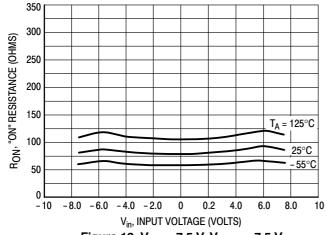


Figure 11. Channel Resistance (R<sub>ON</sub>) Test Circuit

#### TYPICAL RESISTANCE CHARACTERISTICS



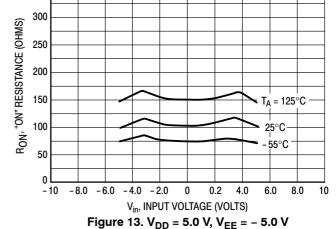
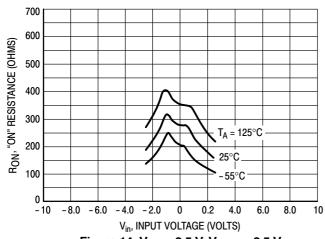


Figure 12.  $V_{DD} = 7.5 \text{ V}, V_{EE} = -7.5 \text{ V}$ 



350  $T_{\Delta} = 25^{\circ}C$ 300 R<sub>ON</sub>, "ON" RESISTANCE (OHMS) 250  $V_{DD} = 2.5 \text{ V}$ 200 150 5.0 V 100 7.5 V 50 -8.0 -6.0 - 4.0 - 2.0 0 4.0 8.0 - 10 0.2 6.0

Figure 14.  $V_{DD}$  = 2.5 V,  $V_{EE}$  = - 2.5 V

 $\label{eq:vin} V_{in}, \text{INPUT VOLTAGE (VOLTS)}$  Figure 15. Comparison at 25°C,  $V_{DD}$  =  $-V_{EE}$ 

#### APPLICATIONS INFORMATION

Figure A illustrates use of the on-chip level converter detailed in Figures 2, 3, and 4. The 0-to-5 V Digital Control signal is used to directly control a 9  $V_{p-p}$  analog signal.

The digital control logic levels are determined by  $V_{DD}$  and  $V_{SS}$ . The  $V_{DD}$  voltage is the logic high voltage; the  $V_{SS}$  voltage is logic low. For the example,  $V_{DD} = +5$  V = logic high at the control inputs;  $V_{SS} = GND = 0$  V = logic low.

The maximum analog signal level is determined by  $V_{DD}$  and  $V_{EE}$ . The  $V_{DD}$  voltage determines the maximum recommended peak above  $V_{SS}$ . The  $V_{EE}$  voltage determines the maximum swing below  $V_{SS}$ . For the example,  $V_{DD} - V_{SS} = 5 \text{ V}$  maximum swing above  $V_{SS}$ ;  $V_{SS} - V_{EE} = 5 \text{ V}$  maximum swing below  $V_{SS}$ . The example shows a  $\pm 4.5 \text{ V}$  signal which allows a 1/2 volt margin at each

peak. If voltage transients above  $V_{DD}$  and/or below  $V_{EE}$  are anticipated on the analog channels, external diodes (Dx) are recommended as shown in Figure B. These diodes should be small signal types able to absorb the maximum anticipated current surges during clipping.

The *absolute* maximum potential difference between  $V_{DD}$  and  $V_{EE}$  is 18.0 V. Most parameters are specified up to 15 V which is the *recommended* maximum difference between  $V_{DD}$  and  $V_{EE}$ .

Balanced supplies are not required. However,  $V_{SS}$  must be greater than or equal to  $V_{EE}$ . For example,  $V_{DD}$  = + 10 V,  $V_{SS}$  = + 5 V, and  $V_{EE}$  – 3 V is acceptable. See the Table below

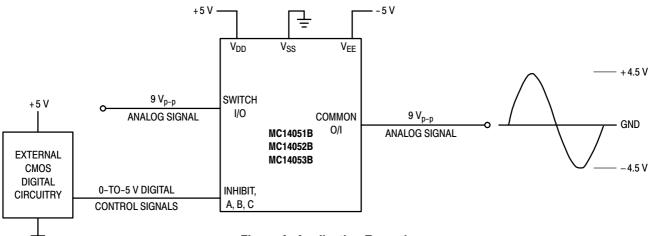


Figure A. Application Example

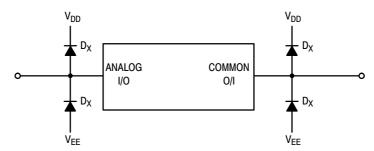


Figure B. External Germanium or Schottky Clipping Diodes

## POSSIBLE SUPPLY CONNECTIONS

V <sub>DD</sub> In Volts	V <sub>SS</sub> In Volts	V <sub>EE</sub> In Volts	Control Inputs Logic High/Logic Low In Volts	Maximum Analog Signal Range In Volts
+ 8	0	-8	+ 8/0	+ 8 to - 8 = 16 V <sub>p-p</sub>
+ 5	0	- 12	+ 5/0	+ 5 to - 12 = 17 V <sub>p-p</sub>
+ 5	0	0	+ 5/0	+ 5 to 0 = 5 V <sub>p-p</sub>
+ 5	0	-5	+ 5/0	+ 5 to - 5 = 10 V <sub>p-p</sub>
+ 10	+ 5	-5	+ 10/ + 5	+ 10 to – 5 = 15 V <sub>p–p</sub>

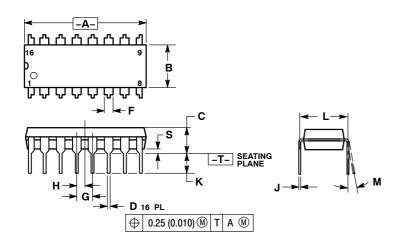
#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MC14051BCPG	PDIP-16 (Pb-Free)	500 Units / Rail
MC14051BDG	SOIC-16 (Pb-Free)	48 Units / Rail
MC14051BDR2G	SOIC-16 (Pb-Free)	2500 / Tape & Reel
MC14051BDTR2G	TSSOP-16*	2500 / Tape & Reel
MC14051BFG	SOEIAJ-16 (Pb-Free)	50 Units / Rail
MC14051BFELG	SOEIAJ-16 (Pb-Free)	2000 / Tape & Reel
MC14052BCPG	PDIP-16 (Pb-Free)	500 Units / Rail
MC14052BDG	SOIC-16 (Pb-Free)	48 Units / Rail
MC14052BDR2G	SOIC-16 (Pb-Free)	2500 / Tape & Reel
MC14052BDTR2G	TSSOP-16*	2500 / Tape & Reel
MC14052BFG	SOEIAJ-16 (Pb-Free)	50 Units / Rail
MC14052BFELG	SOEIAJ-16 (Pb-Free)	2000 / Tape & Reel
MC14053BCPG	PDIP-16 (Pb-Free)	500 Units / Rail
MC14053BDG	SOIC-16 (Pb-Free)	48 Units / Rail
MC14053BDR2G	SOIC-16 (Pb-Free)	2500 / Tape & Reel
MC14053BDTR2G	TSSOP-16*	2500 / Tape & Reel
MC14053BFG	SOEIAJ-16 (Pb-Free)	50 Units / Rail
MC14053BFELG	SOEIAJ-16 (Pb-Free)	2000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. \*This package is inherently Pb-Free.

#### PACKAGE DIMENSIONS

### PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE CASE 648-08 **ISSUE T**

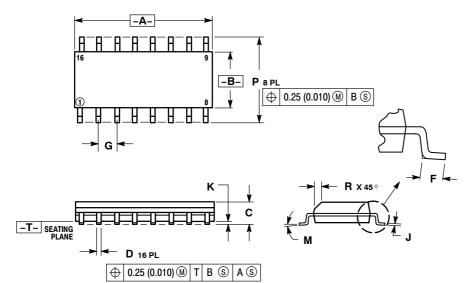


#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
- DIMENSION B DOES NOT INCLUDE MOLD FLASH.
- ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54	BSC	
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
М	0°	10 °	0 °	10 °	
S	0.020	0.040	0.51	1.01	

### SOIC-16 **D SUFFIX** PLASTIC SOIC PACKAGE CASE 751B-05 ISSUE K



#### NOTES:

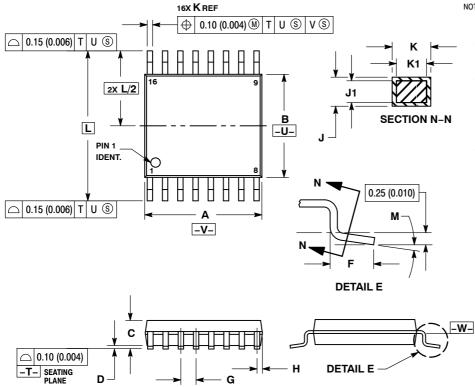
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
  DIMENSIONS A AND B DO NOT INCLUDE MOLD
- PROTRUSION.

  MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
- DIMENSION D DOES NOT INCLUDE DAMBAR
  PROTRUSION. ALLOWABLE DAMBAR PROTRUSION.
  SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D
  DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	9.80	10.00	0.386	0.393	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.25	0.016	0.049	
G	1.27	BSC	0.050 BSC		
J	0.19	0.25	0.008	0.009	
K	0.10	0.25	0.004	0.009	
M	0 °	7°	0°	7°	
Р	5.80	6.20	0.229	0.244	
R	0.25	0.50	0.010	0.019	

#### PACKAGE DIMENSIONS

### TSSOP-16 **DT SUFFIX** PLASTIC TSSOP PACKAGE CASE 948F-01 **ISSUE B**

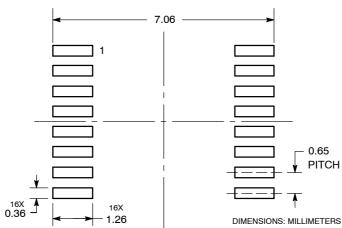


- DIMENSIONING AND TOLERANCING PER ANSI
- DIMENSIONING AND TOLERANCING FER ANSI Y14.5M, 1982.
   CONTROLLING DIMENSION: MILLIMETER.
   DIMENSION A DOES NOT INCLUDE MOLD FLASH.
  PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- SIDE.
  5. DIMENSION K DOES NOT INCLUDE DAMBAR
  PROTRUSION. ALLOWABLE DAMBAR PROTRUSION
  SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K
  DIMENSION AT MAXIMUM MATERIAL CONDITION.

- 6. TERMINAL NUMBERS AT L. S....
  REFERENCE ONLY.
  7. DIMENSION A AND B ARE TO BE DETERMINED AT

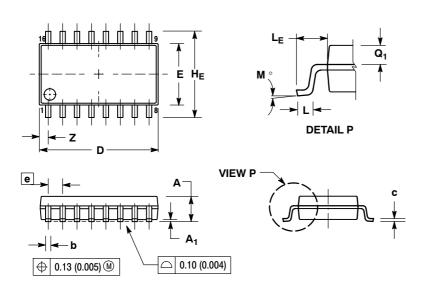
	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	4.90	5.10	0.193	0.200	
В	4.30	4.50	0.169	0.177	
С		1.20		0.047	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.65	BSC	0.026 BSC		
Н	0.18	0.28	0.007	0.011	
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
K	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
L	6.40		0.252	BSC	
М	0°	8°	0 °	8°	

## **SOLDERING FOOTPRINT**



#### PACKAGE DIMENSIONS

### SOEIAJ-16 **F SUFFIX** PLASTIC EIAJ SOIC PACKAGE CASE 966-01 **ISSUE A**



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 114-3M, 1302.

  CONTROLLING DIMENSION: MILLIMETER.

  DIMENSIONS D AND E DO NOT INCLUDE
  MOLD FLASH OR PROTRUSIONS AND ARE
  MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY
- THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
С	0.10	0.20	0.007	0.011
D	9.90	10.50	0.390	0.413
Е	5.10	5.45	0.201	0.215
е	1.27	BSC	0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10°
Q <sub>1</sub>	0.70	0.90	0.028	0.035
Z		0.78		0.031

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